Product/Process Change Notification

N° 2022-214-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting for product family G10.7A DPAK, D2PAK, TO247

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2023-06-19.
- Infineon aligns with the widely-recognized JEDEC STANDARD “JESD46“, which stipulates:
  “Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”
  Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board Dr. Herbert Diess
Management Board Jochen Hanebeck (CEO), Constanze Hufenbecher, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg
Registered office Neubiberg Commercial register Amtsgericht München HRB 126492

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Products affected	Please refer to attached affected product list PCN_2022-214-A_[customer-no].pdf

Detailed change information

Subject:	Several changes affecting for product family G10.7A DPAK, D2PAK, TO247
Reason/Motivation:	Expansion of wafer site production to assure continuity of supply and enable flexible manufacturing.

Description	**Old**	**New**
PROCESS - WAFER PRODUCTION: New wafer diameter	8" wafer diameter (200mm) in Vanguard International Semiconductor Corporation, Hsinchu, Taiwan	8" wafer diameter (200mm) in Vanguard International Semiconductor Corporation, Hsinchu, Taiwan AND 12" wafer diameter (300mm) in Infineon Technologies Dresden GmbH, Dresden ,
PROCESS - WAFER PRODUCTION: New / change of passivation or die coating (without bare die)	SiN/PSG/Imide in Vanguard International Semiconductor Corporation, Hsinchu, Taiwan	SiN/PSG/Imide in Vanguard International Semiconductor Corporation, Hsinchu, Taiwan AND SiN/Imide in Infineon Technologies Dresden GmbH, Dresden , Germany
PROCESS - WAFER PRODUCTION: Move of all or part of wafer fab to a different location/site/subcontractor	Vanguard International Semiconductor Corporation, Hsinchu, Taiwan	Vanguard International Semiconductor Corporation, Hsinchu, Taiwan AND Infineon Technologies Dresden GmbH, Dresden , Germany
EQUIPMENT: Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	Tool park Vanguard AND Too park ETREND	Tool park Vanguard AND Tool park ETREND AND Tool park Dresden

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TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different location/site/subcontractor	SiFo ETREND	SiFo ETREND and Infineon Technologies Dresden GmbH, Dresden , Germany

Product identification	Traceability assured via lot number. No change in SP ordering number
Anticipated impact of change	Based on the qualification performed, Infineon does not expect any negative impact on quality, function and reliability. No change in form, fit and function expected. DeQuMa-ID(s): SEM-PW-02 / SEM-PW-08 / SEM-PW-13 / SEM-EQ-01 / SEM-TF-01

Attachments	PCN_2022-214-A_[customer-no].pdf	affected product list

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2023-11-09
Last order date (LOD) [2]	2023-11-09
Last delivery date (LDD) [3]	2024-11-09

[1] Provided date or earlier after customer approval.
[2] Last date where orders for unchanged products will be accepted.
[3] Last date for delivery of unchanged products. Delivery of changed products can be earlier (see Intended start of delivery) and depends on approval.

If you have any questions, please do not hesitate to contact your local sales office.

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Affected products sold to FUTURE ELECTRONICS INC. (4048203)

Sales name	SP number	OPN	Package	Customer part number
AUIRFR3806TRL	SP001521230	AUIRFR3806TRL	PG-TO252-3-901	
AUIRLR3110ZTRL	SP001516790	AUIRLR3110ZTRL	PG-TO252-3-901	

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Several changes affecting for product family G10.7A DPAK, D2PAK, TO247

Affected products sold to FUTURE ADVANCED ELECTRONICS LIMITED (4066440)

Sales name	SP number	OPN	Package	Customer part number
AUIRLR3110ZTRL	SP001516790	AUIRLR3110ZTRL	PG-TO252-3-901	AUIRLR3110ZTRL

AFFECTED PART NUMBERS
AUIRLR3110ZTRL
SP001516790
AUIRLR3110ZTRL
SP001516790
AUIRFR3806TRL
SP001521230
AUIRFR3806TRL
SP001521230

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Customer approval form

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☐ **Please list product(s) affected in your application(s):**

Please check the appropriate box below:

☐ **We agree with this proposed change and its schedule.**

☐ **We have objections:**

☐ **We need more information:**

☐ **We need samples:**

Sender

Company:

Name:

Address/location:

E-Mail:

Telephone:

Signature

Date:

Product/process change notification

PCN N° 2022-214-A

Please return to your sales partner:

Company: Infineon Technologies AG

Name:

Address/Location :

E-mail:

Telephone: